

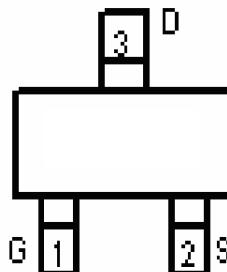


### General Features

- $V_{DS} = -12V, I_D = -4.1A$
- $R_{DS(ON)} < 60m\Omega @ V_{GS}=-2.5V$
- $R_{DS(ON)} < 45m\Omega @ V_{GS}=-4.5V$
- High power and current handing capability
- Lead free product is acquired
- Surface mount package

### Application

- PWM applications
- Load switch
- Power management

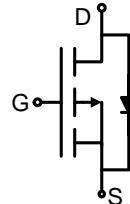


Marking and pin Assignment

### PIN Configuration



SOT-23 top view



Schematic diagram

### Package Marking And Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
	MSP0205A	SOT-23	Ø180mm	8 mm	3000 units

### Absolute Maximum Ratings (TA=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	-12	V
Gate-Source Voltage	$V_{GS}$	$\pm 12$	V
Drain Current -Continuous	$I_D$	-4.1	A
Drain Current -Pulsed (Note 1)	$I_{DM}$	-15	A
Maximum Power Dissipation	$P_D$	1.7	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 150	°C

### Thermal Characteristic

Thermal Resistance,Junction-to-Ambient (Note 2)	$R_{\theta JA}$	74	°C/W
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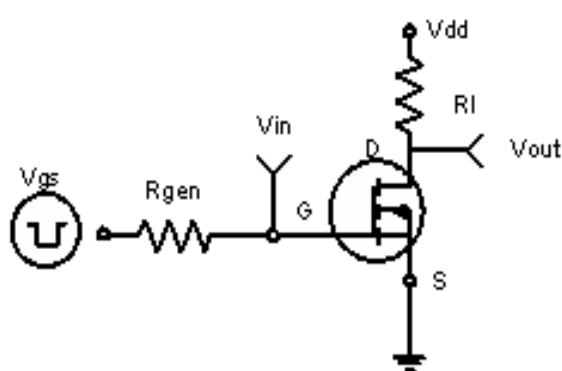
**Electrical Characteristics (TA=25°C unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-12	-18	-	V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS}=-20V, V_{GS}=0V$	-	-	-1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	$\pm 100$	nA
<b>On Characteristics</b> <sup>(Note 3)</sup>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-0.45	-0.7	-1.0	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_D=-4.1A$	-	29	45	$m\Omega$
		$V_{GS}=-2.5V, I_D=-3A$	-	40	60	
Forward Transconductance	$g_{FS}$	$V_{DS}=-5V, I_D=-2A$	5	-	-	S
<b>Dynamic Characteristics</b> <sup>(Note 4)</sup>						
Input Capacitance	$C_{iss}$	$V_{DS}=-4V, V_{GS}=0V, F=1.0MHz$	-	740	-	PF
Output Capacitance	$C_{oss}$		-	290	-	PF
Reverse Transfer Capacitance	$C_{rss}$		-	190	-	PF
<b>Switching Characteristics</b> <sup>(Note 4)</sup>						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-4V, I_D=-3.3A, R_L=-1.2\Omega, V_{GEN}=-4.5V, R_g=1\Omega$	-	12	-	nS
Turn-on Rise Time	$t_r$		-	35	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	30	-	nS
Turn-Off Fall Time	$t_f$		-	10	-	nS
Total Gate Charge	$Q_g$	$V_{DS}=-4V, I_D=-4.1A, V_{GS}=-4.5V$	-	7.8	-	nC
Gate-Source Charge	$Q_{gs}$		-	1.2	-	nC
Gate-Drain Charge	$Q_{gd}$		-	1.6	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage <sup>(Note 3)</sup>	$V_{SD}$	$V_{GS}=0V, I_s=-1.6A$	-	-	-1.2	V
Diode Forward Current <sup>(Note 2)</sup>	$I_s$		-	-	4.1	A

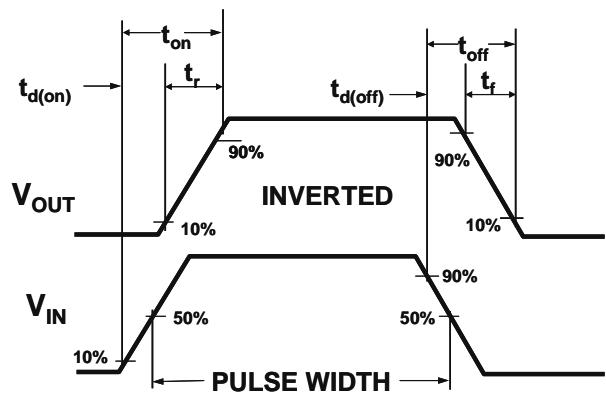
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.
3. Pulse Test: Pulse Width  $\leq 300\mu s$ , Duty Cycle  $\leq 2\%$ .
4. Guaranteed by design, not subject to production

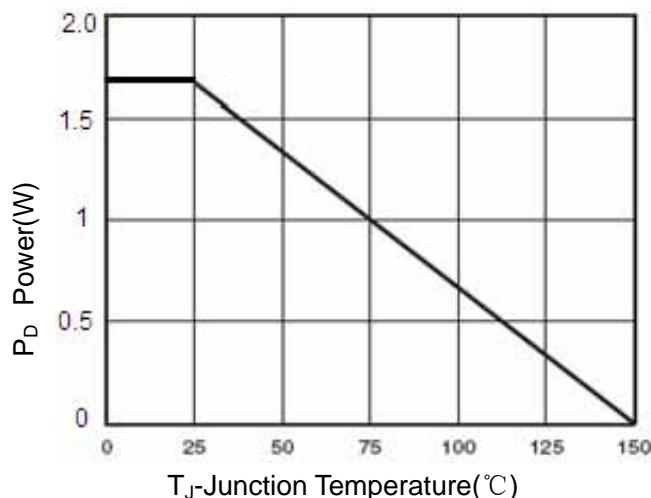
### Typical Electrical and Thermal Characteristics



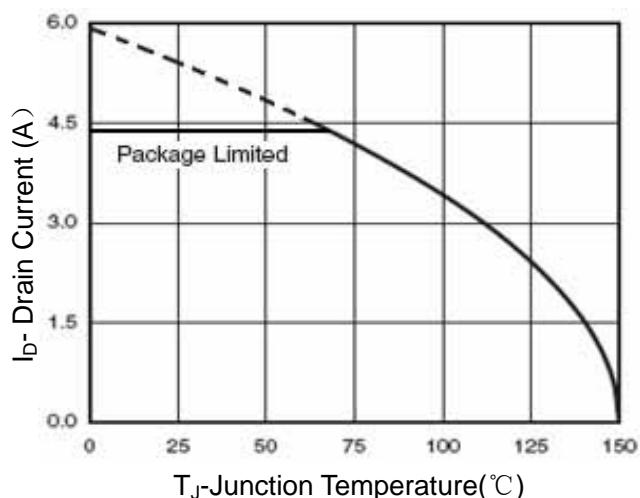
**Figure 1:Switching Test Circuit**



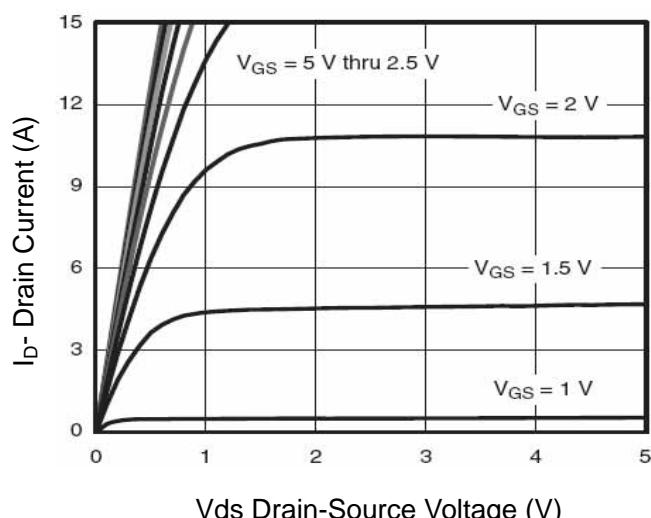
**Figure 2:Switching Waveforms**



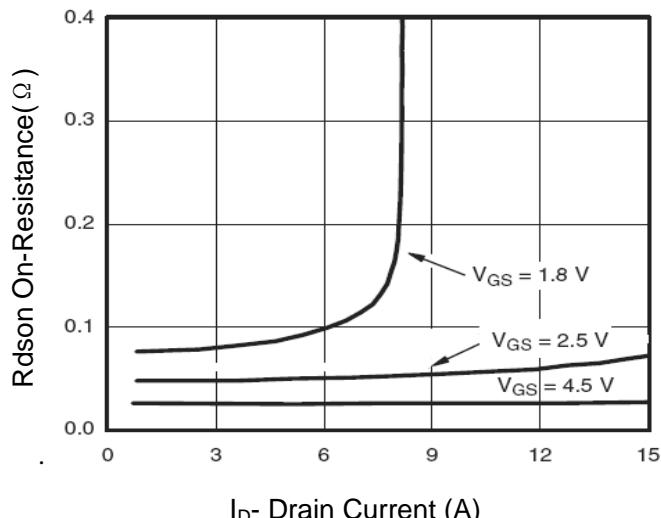
**Figure 3 Power Dissipation**



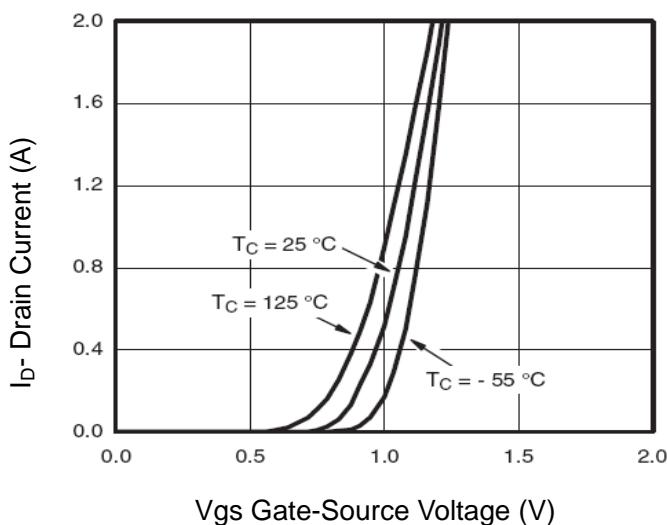
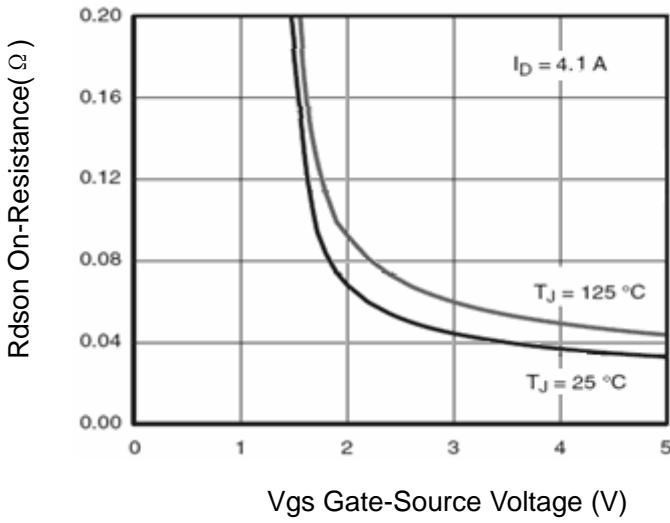
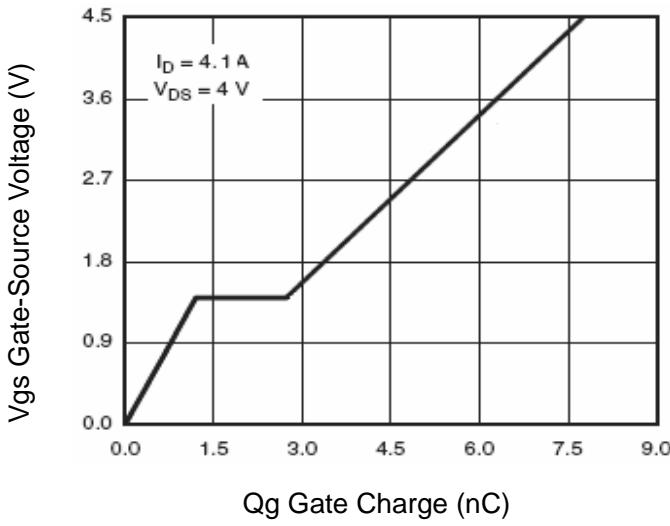
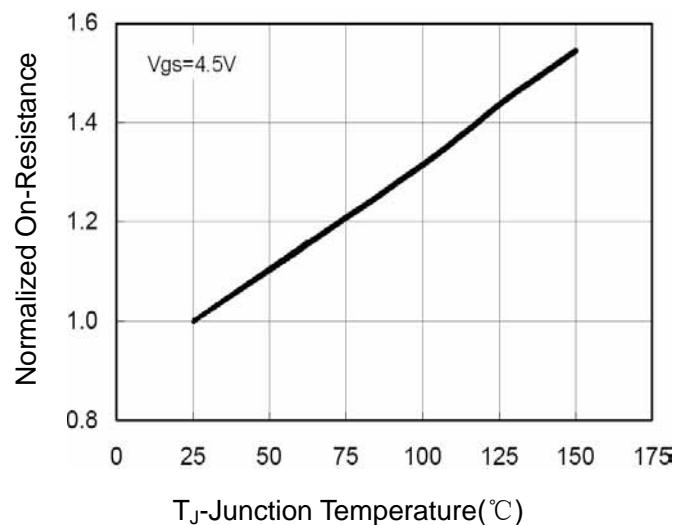
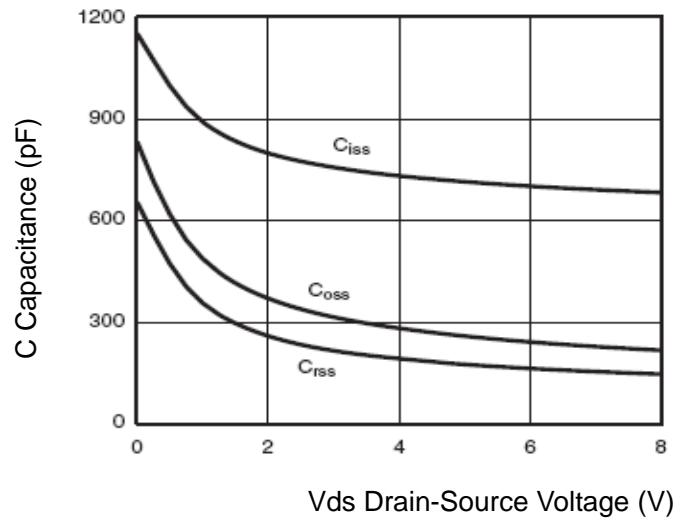
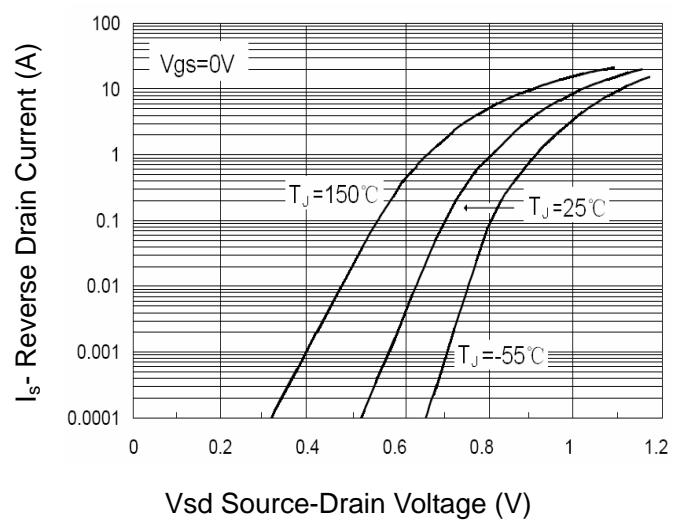
**Figure 4 Drain Current**

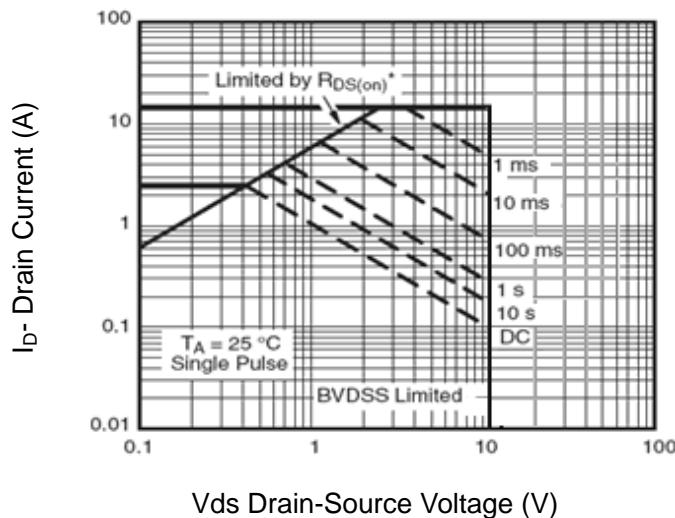


**Figure 5 Output Characteristics**

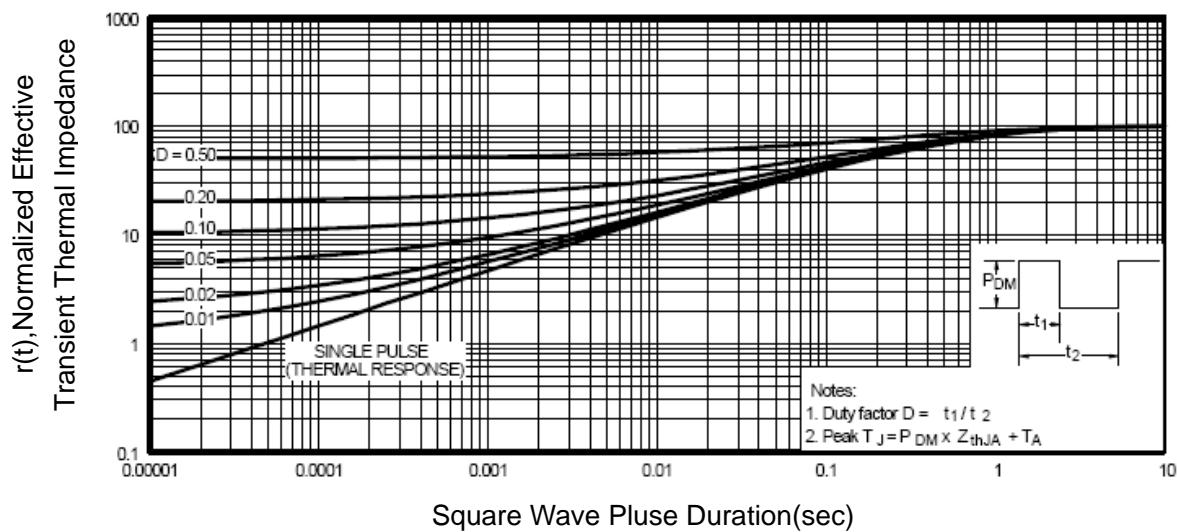


**Figure 6 Drain-Source On-Resistance**

**Figure 7 Transfer Characteristics****Figure 9  $R_{DS(on)}$  vs  $V_{GS}$** **Figure 11 Gate Charge****Figure 8 Drain-Source On-Resistance****Figure 10 Capacitance vs  $V_{DS}$** **Figure 12 Source- Drain Diode Forward**

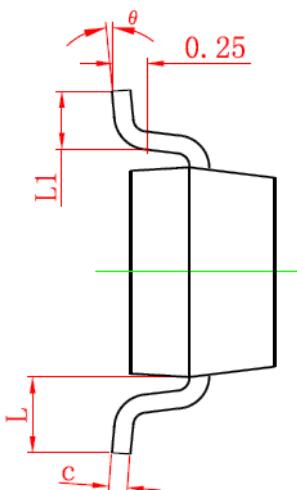
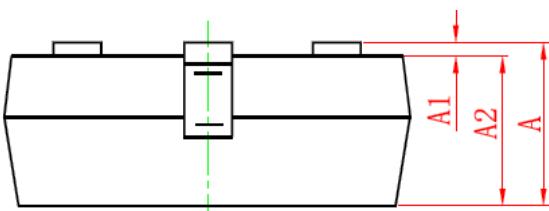
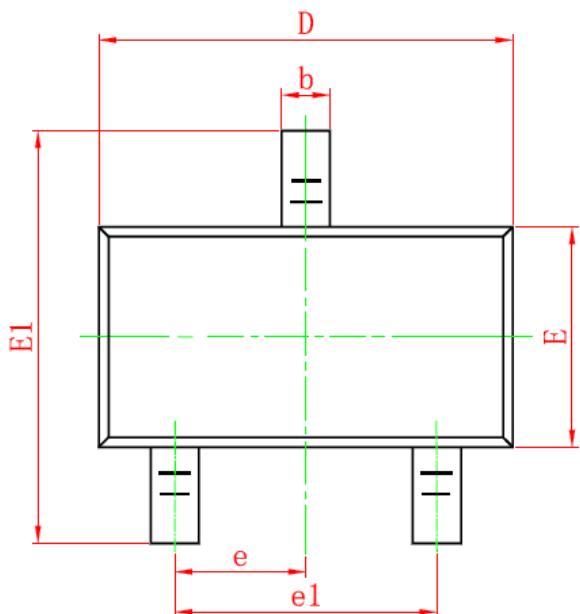


**Figure 13 Safe Operation Area**



**Figure 14 Normalized Maximum Transient Thermal Impedance**

## SOT-23 Package Information



Symbol	Dimensions in Millimeters	
	MIN.	MAX.
<b>A</b>	<b>0.900</b>	<b>1.150</b>
<b>A1</b>	<b>0.000</b>	<b>0.100</b>
<b>A2</b>	<b>0.900</b>	<b>1.050</b>
<b>b</b>	<b>0.300</b>	<b>0.500</b>
<b>c</b>	<b>0.080</b>	<b>0.150</b>
<b>D</b>	<b>2.800</b>	<b>3.000</b>
<b>E</b>	<b>1.200</b>	<b>1.400</b>
<b>E1</b>	<b>2.250</b>	<b>2.550</b>
<b>e</b>	<b>0.950TYP</b>	
<b>e1</b>	<b>1.800</b>	<b>2.000</b>
<b>L</b>	<b>0.550REF</b>	
<b>L1</b>	<b>0.300</b>	<b>0.500</b>
<b>θ</b>	<b>0°</b>	
	<b>8°</b>	

## Notes

1. All dimensions are in millimeters.
2. Tolerance  $\pm 0.10\text{mm}$  (4 mil) unless otherwise specified
3. Package body sizes exclude mold flash and gate burrs. Mold flash at the non-lead sides should be less than 5 mils.
4. Dimension L is measured in gauge plane.
5. Controlling dimension is millimeter, converted inch dimensions are not necessarily exact.